

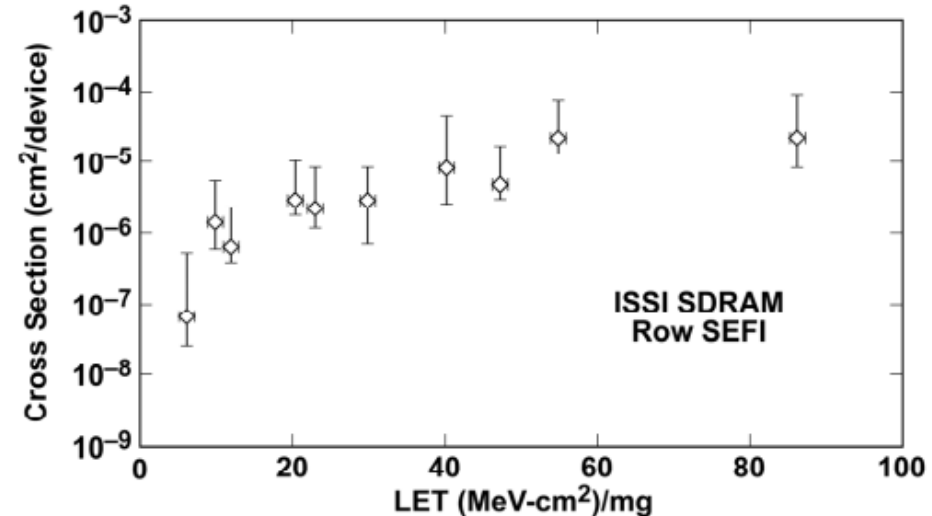
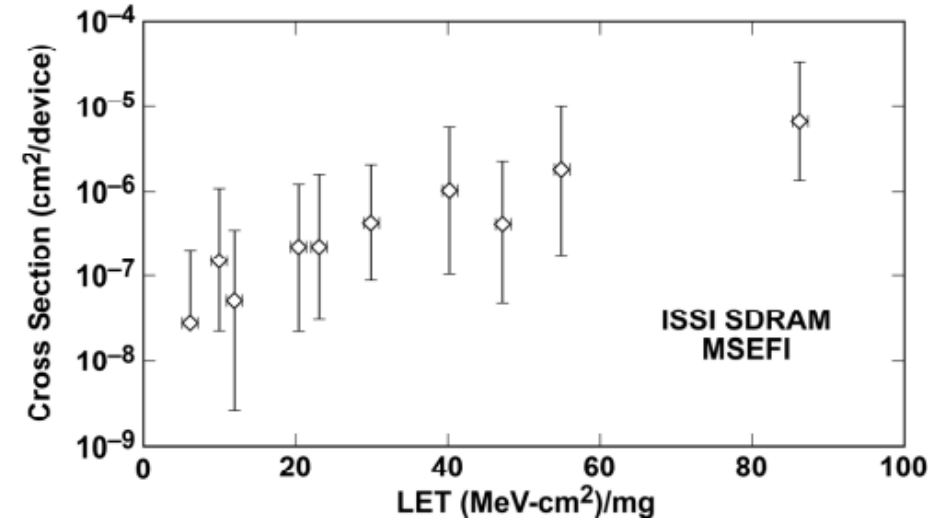
Test Results on SDRAM IS42S86400B-7TLI

Thierry BONNOIT
Maximilien GLORIEUX
Cesar BOATELLA POLO

29 June 2023

Context and Objectives

- [1][2] reported important SEFI mechanism on ISSI IS42S86400B-7TL SDRAM
 - Million SEFI: Million errors induced by one ionizing particle impact
 - Row/Column SEFI: Set of row/Column with a large number of errors
- Objectives:
 - Reproduce SEFI with LASER attack:
 - Identify sensitive area and event signature
 - Explore mitigation options
 - Measure HI sensitivity
 - Evaluate LEON4 EDAC capability to detect and correct SEFI induced errors



[1]: F. Irom and M. Amrbar, "Heavy Ion Single Event Effects Measurements of 512Mb ISSI SDRAM," 2015 IEEE Radiation Effects Data Workshop (REDW), Boston, MA
[2]: G. R. Allen *et al.*, "2015 Compendium of Recent Test Results of Single Event Effects Conducted by the Jet Propulsion Laboratory's Radiation Effects Group," 2015 IEEE Radiation Effects Data Workshop (REDW), Boston, MA

LASER Test Approach Overview

- CNES Laser Facility characteristics:
 - Single photon absorption
 - Wavelength: 1064nm
 - Pulse energy: up to 2.5nJ per pulse
 - Pulse picket to reduce pulse frequency
 - Pulse duration: 7.5ps
 - 1X to 50X lens
 - Range: 13x13 mm to 250x250 μm
 - Resolution: 22 μm to 0.9 μm
- Dynamic test algorithm with flexible options:
 - Operation order
 - Data pattern
 - Address sequence



LASER Experiment Sizing

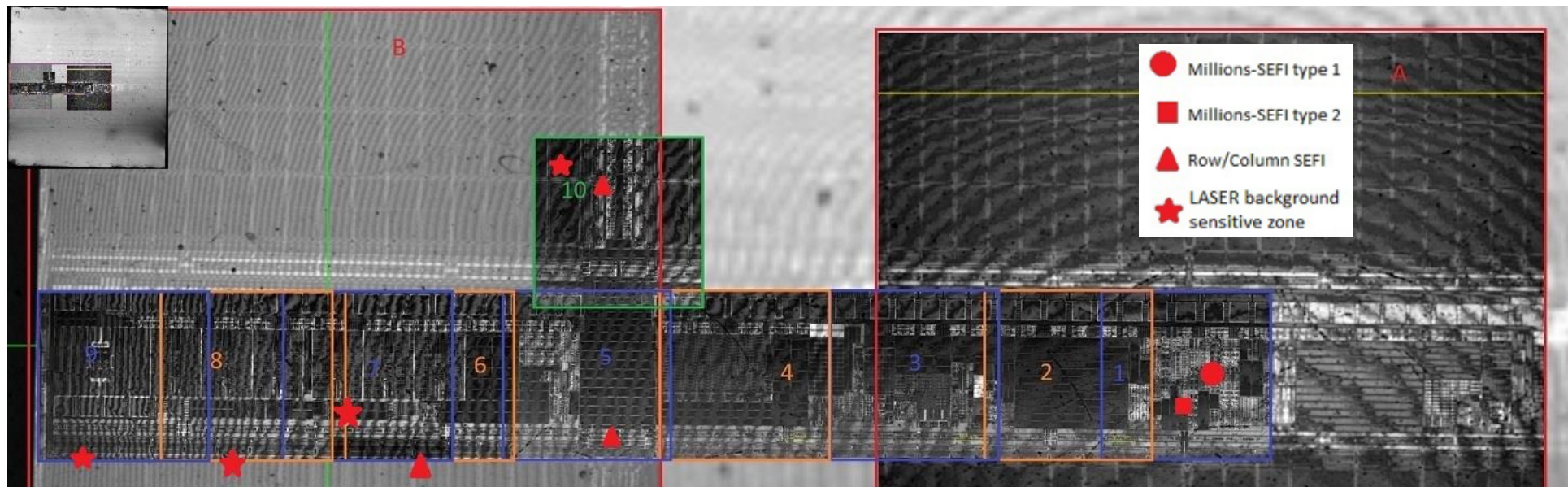
- 50 MHz operation: complete R/W operation duration is 1.4s
- Die area is 9.1x9.1 mm
- Overall scan duration (512x512 pixel per zone):

Lens	Scannable area	Number of zone	Duration
1X	13×13 mm	1	4 days/scan
5X	2.5×2.5 mm	16	68 days/scan
20X	650×650 μm	196	2 years/scan
50X	250×250 μm	1369	16 years/scan

- Possible options:
 - Increase number of laser hit per memory operation
 - Reduce the address range of memory operation
 - Select scanned area

LASER Test Results

- 2 Million SEFI Mechanisms identified
- Row and Column SEFI were observed
- Some regions sensitive to LASER charge accumulation
- Other events (SEU, MBU, MCU, Transients)



Million SEFI Type 1

- Not related to a specific address range and data pattern
- For most of observed events:
 - Similar erroneous data was read at each address (independently of the test pattern)
 - Each address has a specific erroneous data pattern
- Most of the errors are corrected after a write operation but:
 - Few address are still not operating correctly
 - If the refresh is disabled, much more address are not operating correctly
 - The uncorrectable errors seem weak cells / stuck bits
- Power cycle needed to recover
- Possible explanation:
 - Upsets in the memory physical mapping tables that are usually loaded at power on and are not accessible by the user

Million SEFI Type 2

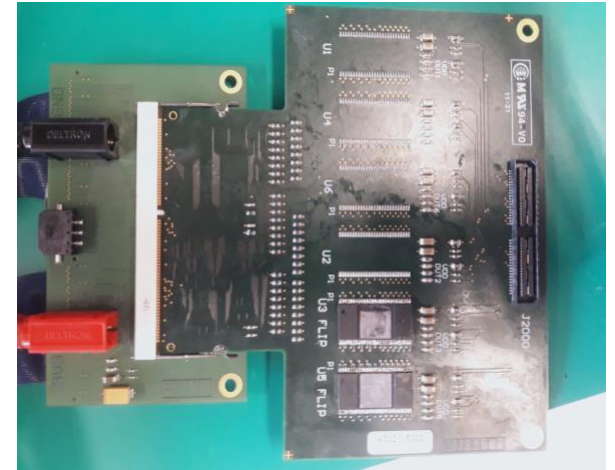
- Upsets in the memory configuration register
 - Modification of the burst sequence
 - New burst configuration is either “000” or “111”
 - Upset of the “Single location address” and “Sequential/Interleaving” bits
 - CAS bit was not upset
- Using a burst of size 1 allows to mask this SEFI
- Re-writing the configuration register correct the SEFI
 - Stored data is not lost and can be read afterward
 - If some write operations were performed, they may not be performed correctly

LASER Charge Accumulation

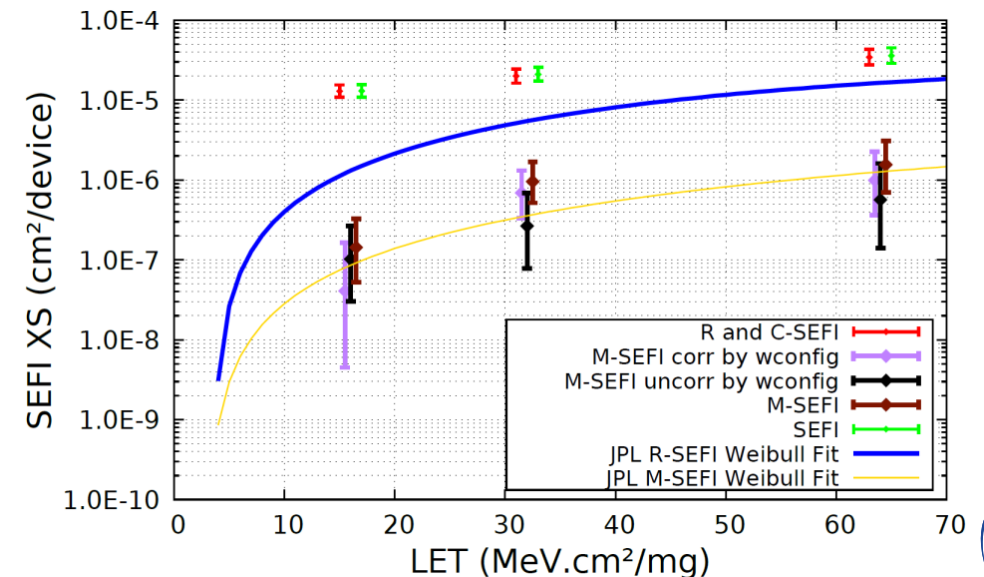
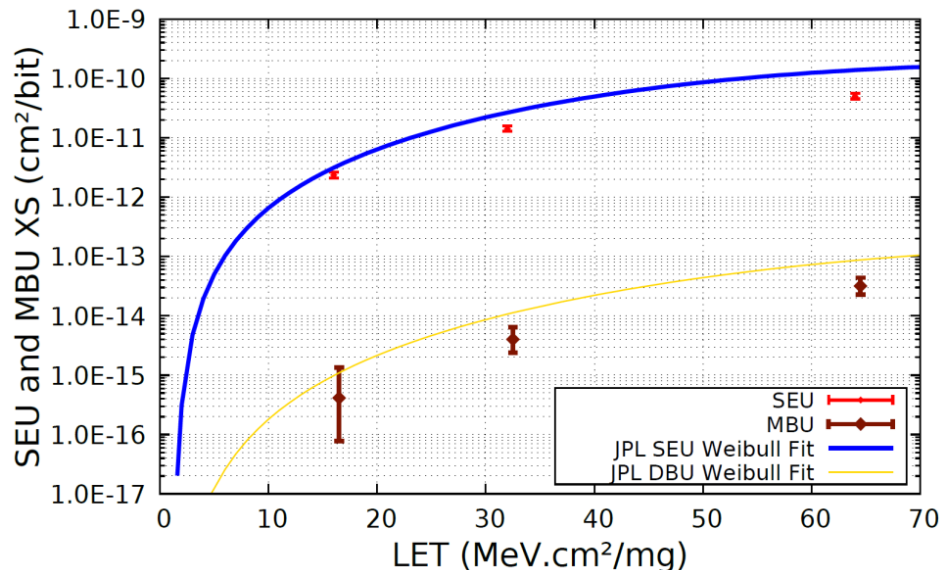
- When LASER energy is increased, some regions are sensitive to the remaining energy not filtered by the pulse picker
 - All address are erroneous
 - Output is tied to 0xFF
- This is a test artifact!
- Observed at several location on the die

Stand-alone HI Tests

- Objective
 - Reproduce SEFI events and measure XS
- SEU – MBU
 - Consistent with JPL results



- SEFIs
 - M-SEFI 1 and 2 observe as in LASER
 - Other SEFI mechanisms identified



System HI Tests with GR740 LEON4

- ISSI as main memory of GR740 LEON4
 - Assess EDAC capability to detect/correct SEFIs
 - 2 devices irradiated simultaneously
- GR740 EDACs are based on 4 bits nibbles
 - 1 nibble error can be corrected
 - Bus data width: 64 or 32 bits (data wrote on 2 consecutive address)
 - 2 interleaving scheme:
 - Mode A: 4 group of 16 bits
 - Mode B: 2 group of 32 bits
 - Test performed in mode A – 32 bits



Table 89. Mode Ax4 interleaving pattern (64-bit data width)																							
63:60	59:56	55:52	51:48	47:44	43:40	39:36	35:32	31:28	27:24	23:20	19:16	15:12	11:8	7:4	3:0								
C	D	A	B	A	B	C	D	B	A	D	C	D	C	B	A								
<table> <tr> <td>C_{cb}</td><td>D_{cb}</td><td>A_{cb}</td><td>B_{cb}</td><td>C_{cb}</td><td>D_{cb}</td><td>A_{cb}</td><td>B_{cb}</td></tr> </table>																C _{cb}	D _{cb}	A _{cb}	B _{cb}	C _{cb}	D _{cb}	A _{cb}	B _{cb}
C _{cb}	D _{cb}	A _{cb}	B _{cb}	C _{cb}	D _{cb}	A _{cb}	B _{cb}																

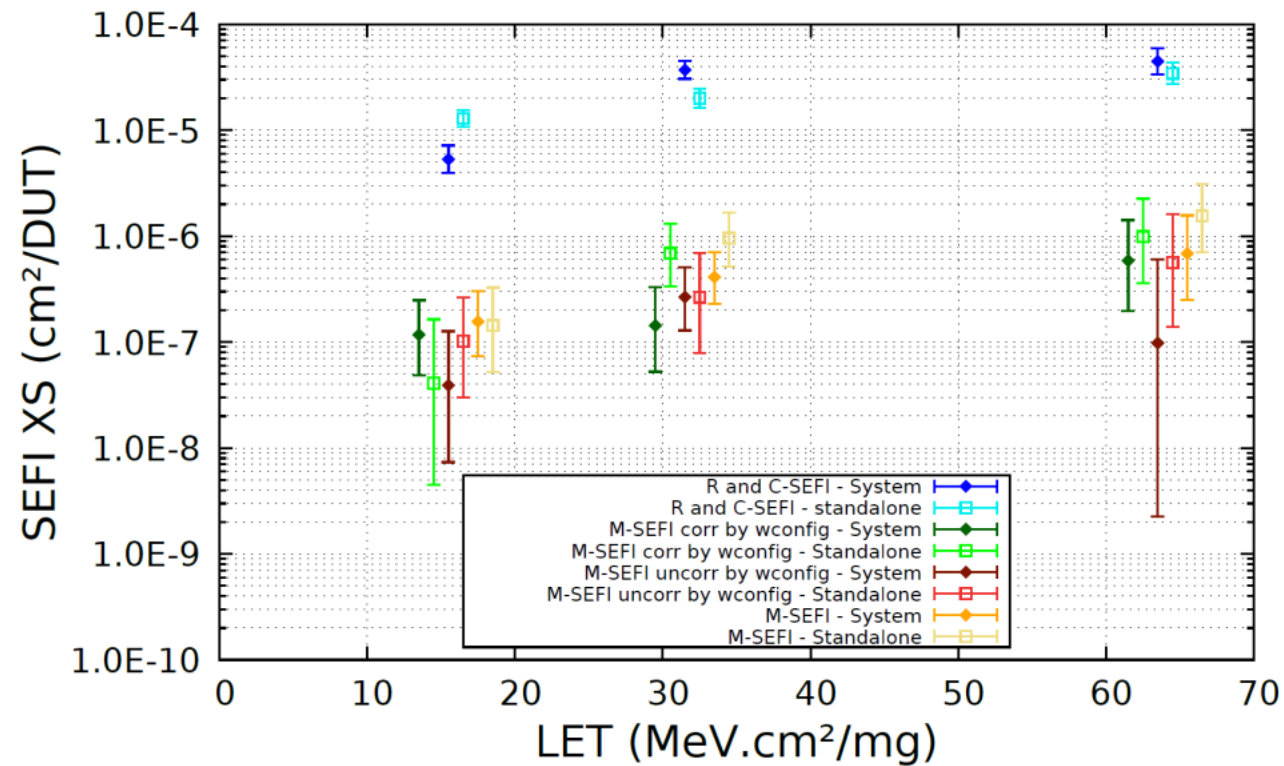
Table 90. Mode Bx2 interleaving pattern (64-bit data width)																							
63:60	59:56	55:52	51:48	47:44	43:40	39:36	35:32	31:28	27:24	23:20	19:16	15:12	11:8	7:4	3:0								
A	B	A	B	A	B	A	B	B	A	B	A	B	A	B	A								
<table> <tr> <td>A_{cb}</td><td>B_{cb}</td><td>A_{cb}</td><td>B_{cb}</td><td>A_{cb}</td><td>B_{cb}</td><td>A_{cb}</td><td>B_{cb}</td></tr> </table>																A _{cb}	B _{cb}	A _{cb}	B _{cb}	A _{cb}	B _{cb}	A _{cb}	B _{cb}
A _{cb}	B _{cb}	A _{cb}	B _{cb}	A _{cb}	B _{cb}	A _{cb}	B _{cb}																

Table 91. Mode Ax4 interleaving pattern (32-bit data width)													
95:80	79:76	75:72	71:68	67:64	63:32	31:28	27:24	23:20	19:16	15:12	11:8	7:4	3:0
-	C _{cb}	D _{cb}	A _{cb}	B _{cb}	-	C	D	A	B	A	B	C	D
-	B _{cb}	A _{cb}	D _{cb}	C _{cb}	-	B	A	D	C	D	C	B	A

Table 92. Mode Bx2 interleaving pattern (32-bit data width)													
95:80	79:76	75:72	71:68	67:64	63:32	31:28	27:24	23:20	19:16	15:12	11:8	7:4	3:0
-	-	-	A _{cb}	B _{cb}	-	A	B	A	B	A	B	A	B
-	-	-	B _{cb}	A _{cb}	-	B	A	B	A	B	A	B	A

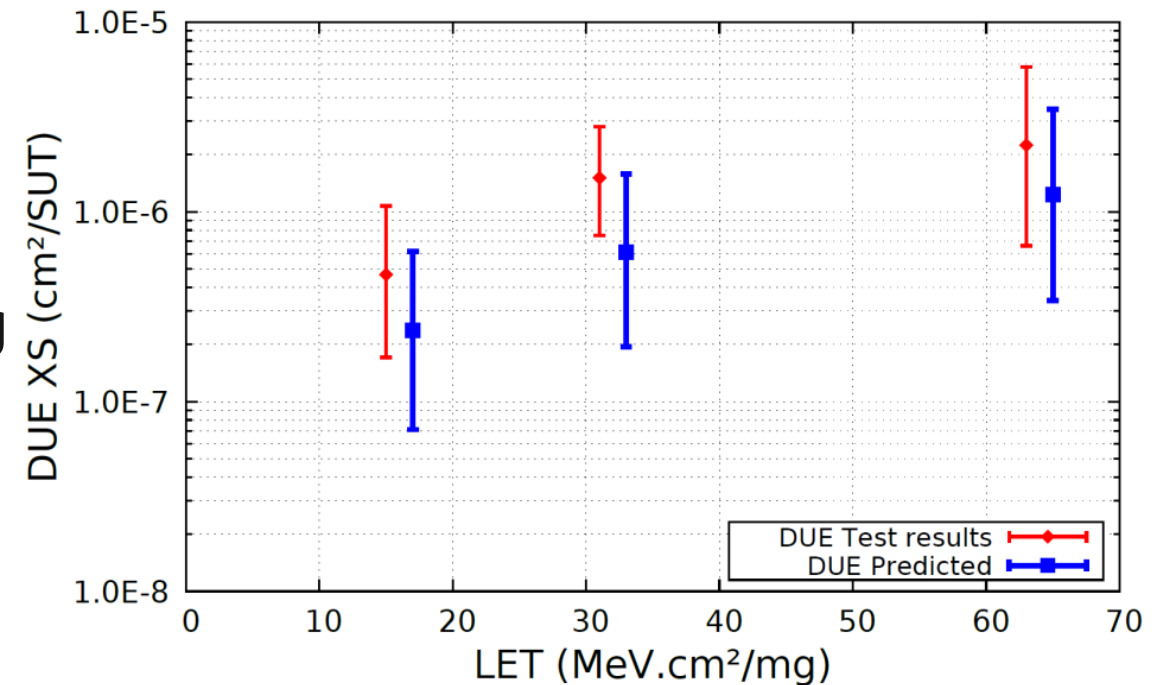
System Test Results

- Test algorithm implemented in software, in the LEON4 CPU
- EDAC error counters used to identify SEFIs
- Similar cross-section as stand-alone test



Detectable Uncorrectable Errors

- GR740 SDRAM are protected with Reed-Solomon ECC
 - EDAC is able to correct data even if one SDRAM device is not functional
 - DUE occurs if two nibbles are erroneous
 - SEFI + SEFI
 - SEFI + SEU
- DUE are detected by LEON4 interruption when the corresponding address is read
 - DUE XS depends on software execution flow
 - XS is reported for the system



Impact of EDAC Configuration

- The impact of EDAC mode was assessed analytically
 - EDAC can correct one nibble error per group
 - In mode A 64/32 bit or B 64 bits:
 - a M-SEFI impact one nibble / group
 - $P(DUE) = P(Ev_1 \cap Ev_2)$
 - Ev_1/Ev_2 is M-SEFI, R/C-SEFI or SEU
 - $P(A - 64) = 2 \times P(A - 32)$ but system memory is 2 times larger in 64 bit mode
 - In mode B 32 bits:
 - SEFI impact two nibble / group
 - Any SEFI will lead to DUE
 - $P(DUE) = N_{DUT} \times P(SEFI)$

Table 89. Mode Ax4 interleaving pattern (64-bit data width)

63:60	59:56	55:52	51:48	47:44	43:40	39:36	35:32	31:28	27:24	23:20	19:16	15:12	11:8	7:4	3:0
C	D	A	B	A	B	C	D	B	A	D	C	D	C	B	A
127:120	119:112	111:104	103:96	95:88	87:80	79:72	71:64	C _{cb}	D _{cb}	A _{cb}	B _{cb}	C _{cb}	D _{cb}	A _{cb}	B _{cb}

Table 90. Mode Bx2 interleaving pattern (64-bit data width)

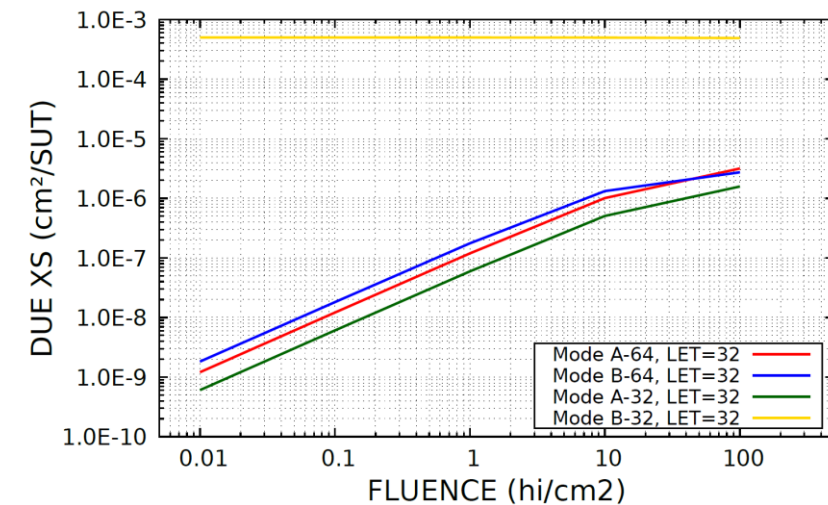
63:60	59:56	55:52	51:48	47:44	43:40	39:36	35:32	31:28	27:24	23:20	19:16	15:12	11:8	7:4	3:0
A	B	A	B	A	B	A	B	B	A	B	A	B	A	B	A
95:88	87:80	79:72	71:64	A _{cb}	B _{cb}	A _{cb}	B _{cb}								

Table 91. Mode Ax4 interleaving pattern (32-bit data width)

95:80	79:76	75:72	71:68	67:64	63:32	31:28	27:24	23:20	19:16	15:12	11:8	7:4	3:0
-	C _{cb}	D _{cb}	A _{cb}	B _{cb}	-	C	D	A	B	A	B	C	D
-	B _{cb}	A _{cb}	D _{cb}	C _{cb}	-	B	A	D	C	D	C	B	A

Table 92. Mode Bx2 interleaving pattern (32-bit data width)

95:80	79:76	75:72	71:68	67:64	63:32	31:28	27:24	23:20	19:16	15:12	11:8	7:4	3:0
-	-	-	A _{cb}	B _{cb}	-	A	B	A	B	A	B	A	B
-	-	-	B _{cb}	A _{cb}	-	B	A	B	A	B	A	B	A



GEO Error Rate Estimations

- GEO DUE probability was estimated considering a memory restore cycle each hour
 - Memory restore cycle is write config register + memory scrubbing
- 15 year GEO mission, with 3.7 mm of Al spherical shielding
- As only 3 LET are available, simple error calculation is performed
- In mode B - 32 bit, it corresponds to the probability to get a SEFI during the mission

ECC Mode	P(DUE) in 1h	P(DUE) in 15y
A – 64 bit	2.16E-9	0.028%
B – 64 bit	3.23E-9	0.042%
A – 32 bit	1.08E-9	0.014%
B – 32 bit	1.74E-4	100%

Conclusions

- Several SEFI mechanism were identified and observed with LASER
 - Some cannot be corrected with write config register (power cycle needed)
- LASER experiment is a good preparation for complex HI test but
 - Experiment sizing can be difficult
 - LASER experiment is not exhaustive
- LASER results helpful to prepare post-processing scripts
- Stand-alone HI test provided similar results as JPL
- System test shown that GR740 EDACs can correct SEFIs
 - DUE still possible in case of SEFI+SEU or SEFI+SEFI on several memory components
 - GEO mission DUE very unlikely in mode A or B-64 bits
 - EDACs mode B-32 bits not well hardened against SEFI/permanent faults